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Foreword

Over the last year we have been working to expand and improve the content of this Journal. This process has taken several forms including a new format, an expansion of the editorial board, and a more robust review process that is used to ensure the quality and relevance of the content that we publish. This quarter we are continuing that process by welcoming our newest associate editor, Professor Tae-Sung Oh from Korea.

Dr. Oh has been a Professor at the Department of Materials Science and Engineering of Hongik University, Seoul, Korea, since 1992. Professor Oh is currently working in the areas of chip-stack packaging, flip-chip processing, and thermoelectric materials and devices. He received his B.S. Degree in Metallurgical Engineering from Seoul National University, Seoul, Korea, in 1978, and his M.S. and Ph.D. degrees in Materials Science and Engineering from the University of California, Berkeley in 1986 and 1988, respectively. After receiving his Ph.D. degree, he worked at the IBM Watson research center from 1988-1990 and at the Korea Institute of Science and Technology from 1990-1992. His strong background and active research program will be a great asset for the Journal, and it is a privilege to be able to work with him on this publication.

We are also in the process of investing in a software tool that will enable web based submission of manuscripts to this journal. This new capability will also provide a web interface for the review process and enable authors to track the status of their papers during the review and publication stages. By automating some of the tasks associated with these processes, we will be able to increase efficiency and reduce the overall time from the date of submission to the publication date.

Fred D. Barlow III, Ph.D.
Editor-in-Chief

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